



110-25

FLEXIBLE, HOT MELT ADHESIVE

DESCRIPTION: 110-25 is a flexible, thermoplastic, hot melt adhesive. This product features excellent adhesion to Kapton, Mylar, glass, and metals, as well as a variety of other substrates. This product is very resistant to flexing and creasing and can be re-bonded many times by simply applying heat and slight pressure. 110-25 is useful for applications requiring flexibility at very low temperatures. This product is a faster drying, unfilled version of 107-36 that ref-lows at a lower temperature.

TYPICAL CURED PROPERTIES:

Consistency	Liquid
Crease Resistance	Excellent
Volume Resistance (Ω -cm)	1×10^{12}
Hydrolytic Stability	Excellent
Useful Temperature Range ($^{\circ}$ C)	-55 to 100
Thermal Stability ($^{\circ}$ C)	Good to 200
Glass Transition Temp. ($^{\circ}$ C)	-11

SUGGESTED HANDLING & CURING: 110-25 is ready to use as supplied. Further thinning may be accomplished by adding small amounts of MEK if faster drying times are required. Best properties, for most applications, result when allowed to dry at room temperature followed by curing for 5-10 minutes at 110° C. Good properties are obtained on a variety of substrates by curing at temperatures ranging from 50° C to 110° C. When used as a sealant, apply adhesive to surfaces to be bonded and dry for several minutes at room temperature, then place substrates together while heating and applying slight pressure. End user is advised to experimentally determine temperature and time best suited for individual applications.

STORAGE: Shelf life: 6 months at 25° C; or 9 months at 5° C; or 12 months at -10° C.

SAFETY & HANDLING: Use with adequate ventilation. Keep away from sparks and open flames. Avoid prolonged contact with skin and breathing of vapors. Wash with soap and water to remove from skin.

All technical information is based on data obtained by CMI personnel and is believed to be reliable. No warranty is either expressed or implied with respect to suitability in a particular application or possible infringements on patents.

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